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ON Semiconductor®

IRFNL210B

N-Channel B-FET

200 V, 1.0 A, 1.5 Ω

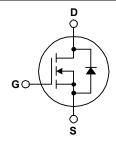
Description

These N-Channel enhancement mode power field effect transistors are produced using $O\dot{N}$ Semiconductor's proprietary, planar, DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency switching DC/DC converters, switch mode power supplies, DC-AC converters for uninterrupted power supply and motor control.

Features

- 1.0 A, 200 V, R_{DS(on)} = 1.5 Ω @ V_{GS} = 10 V Low Gate Charge (typical 7.2 nC)
- Low Crss (typical 6.8 pF)
- Fast Switching
- 100% Avalanche Tested
- Improved dv/dt Capability





Absolute Maximum Ratings T_C = 25°C unless otherwise noted.

Symbol	Parameter		IRFNL210BTA-FP001	Unit	
V_{DSS}	Drain-Source Voltage		200	V	
I _D	Drain Current - Continuous (T _C = 25	°C)	1.0	Α	
	- Continuous (T _C = 10	0°C)	0.93	Α	
I _{DM}	Drain Current - Pulsed	(Note 1)	10	А	
V _{GSS}	Gate-Source Voltage		± 30	V	
E _{AS}	Single Pulsed Avalanche Energy	(Note 2)	40	mJ	
I _{AR}	Avalanche Current	(Note 1)	3.3	Α	
E _{AR}	Repetitive Avalanche Energy	(Note 1)	0.031	mJ	
dv/dt	Peak Diode Recovery dv/dt	(Note 3)	5.0	V/ns	
P_{D}	Power Dissipation (T _C = 25°C)		3.1	W	
	- Derate above 25°C		0.025	W/°C	
T _J , T _{STG}	Operating and Storage Temperature Ra	nge	-55 to +150	°C	
T _L	Maximum lead temperature for soldering 1/8" from case for 5 seconds	g purposes,	300	°C	

Thermal Characteristics

Symbol	Parameter	IRFNL210BTA-FP001	Unit
$R_{\theta JL}$	Thermal Resistance, Junction-to-Lead, Max.	40	°C/W

Package Marking and Ordering Information

Part Number	Top Mark	Package	Packing Method	Reel Size	Tape Width	Quantity
IRFNL210BTA-FP001	210B	TO-92L	AMMO	N/A	N/A	2000 units

Electrical Characteristics T_c = 25°C unless otherwise noted.

Parameter	Test Conditions	Min	Тур	Max	Units
racteristics					
Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	200			V
Breakdown Voltage Temperature Coefficient	I _D = 250 μA, Referenced to 25°C		0.2		V/°C
Zara Cata Valtara Drain Current	V _{DS} = 200 V, V _{GS} = 0 V			10	μΑ
Zero Gate Voltage Drain Current	V _{DS} = 160 V, T _C = 125°C			100	μΑ
Gate-Body Leakage Current, Forward	V _{GS} = 30 V, V _{DS} = 0 V			100	nA
Gate-Body Leakage Current, Reverse	V _{GS} = -30 V, V _{DS} = 0 V			-100	nA
	Drain-Source Breakdown Voltage Breakdown Voltage Temperature Coefficient Zero Gate Voltage Drain Current Gate-Body Leakage Current, Forward	tracteristics Drain-Source Breakdown Voltage $V_{GS} = 0 \text{ V}$, $I_D = 250 \text{ μA}$ Breakdown Voltage Temperature Coefficient $I_D = 250 \text{ μA}$, Referenced to 25°C Zero Gate Voltage Drain Current $V_{DS} = 200 \text{ V}$, $V_{GS} = 0 \text{ V}$ VDS = 160 V, $V_{CS} = 125 \text{ C}$ Gate-Body Leakage Current, Forward $V_{CS} = 30 \text{ V}$, $V_{DS} = 0 \text{ V}$	$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$

On Characteristics

V _{GS(th)}	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$	2.0		4.0	V
R _{DS(on)}	Static Drain-Source On-Resistance	$V_{GS} = 10 \text{ V}, I_D = 0.5 \text{ A}$		1.16	1.5	Ω
9 _{FS}	Forward Transconductance	$V_{DS} = 40 \text{ V}, I_{D} = 1.0 \text{ A}$		2.4		S

Dynamic Characteristics

C_{iss}	Input Capacitance	$V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V},$	 175	225	pF
Coss	Output Capacitance	f = 1.0 MHz	 30	40	pF
C _{rss}	Reverse Transfer Capacitance		 6.8	9.0	pF

Switching Characteristics

t _{d(on)}	Turn-On Delay Time	V _{DD} = 100 V, I _D = 3.3 A,	 5.2	20	ns
t _r	Turn-On Rise Time	$R_G = 25 \Omega$	 35	80	ns
t _{d(off)}	Turn-Off Delay Time		 20	50	ns
t _f	Turn-Off Fall Time	(Note 4)	 25	60	ns
Q_g	Total Gate Charge	V _{DS} = 160 V, I _D = 3.3 A,	 7.2	9.3	nC
Q_{gs}	Gate-Source Charge	V _{GS} = 10 V	 1.3		nC
Q _{gd}	Gate-Drain Charge	(Note 4)	 3.5		nC

Drain-Source Diode Characteristics and Maximum Ratings

I _S	Maximum Continuous Drain-Source Diode Forward Current				3.3	Α
I _{SM}	Maximum Pulsed Drain-Source Diode Forward Current				10	Α
V _{SD}	Drain-Source Diode Forward Voltage	$V_{GS} = 0 \text{ V}, I_{S} = 3.3 \text{ A}$			1.5	V
t _{rr}	Reverse Recovery Time	$V_{GS} = 0 \text{ V}, I_{S} = 3.3 \text{ A},$		106		ns
Q _{rr}	Reverse Recovery Charge	$dI_F / dt = 100 A/\mu s$		0.37		μС

- **Notes:** 1. Repetitive rating: pulse-width limited by maximum junction temperature. 2. L = 5.5 mH, I_{AS} = 3.3 A, V_{DD} = 50 V, R_G = 25 Ω , Starting T_J = 25°C. 3. I_{SD} \leq 3.3 A, di/dt \leq 300 A/ μ s, V_{DD} \leq BV_{DSS}, Starting T_J = 25°C. 4. Essentially independent of operating temperature.

Typical Characteristics

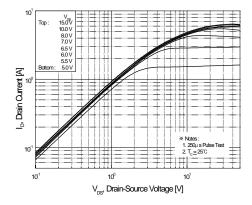


Figure 1. On-Region Characteristics

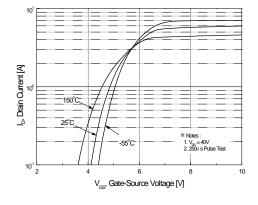


Figure 2. Transfer Characteristics

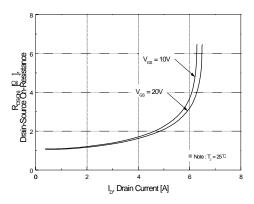


Figure 3. On-Resistance Variation vs Drain Current and Gate Voltage

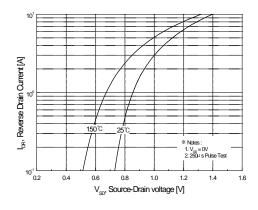


Figure 4. Body Diode Forward Voltage Variation with Source Current and Temperature

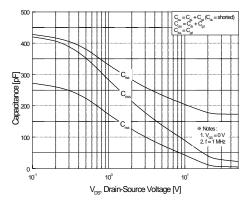


Figure 5. Capacitance Characteristics

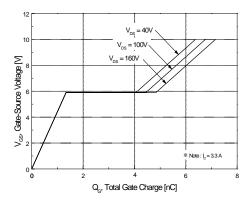


Figure 6. Gate Charge Characteristics

Typical Characteristics (continued)

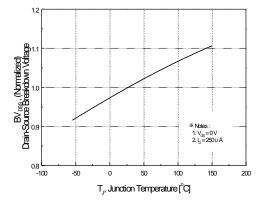


Figure 7. Breakdown Voltage Variation

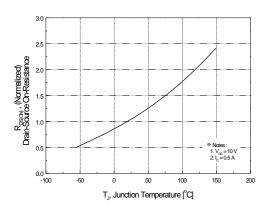


Figure 8. On-Resistance Variation vs Temperature

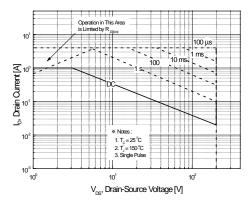


Figure 9. Maximum Safe Operating Area

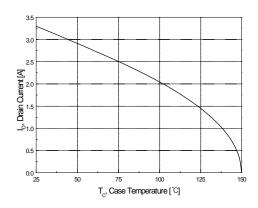


Figure 10. Maximum Drain Current vs Case Temperature

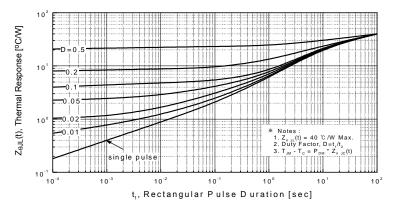


Figure 11. Transient Thermal Response Curve

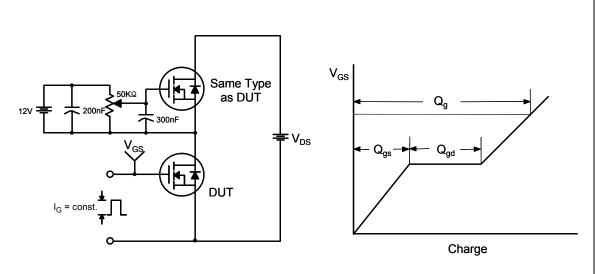


Figure 12. Gate Charge Test Circuit & Waveform

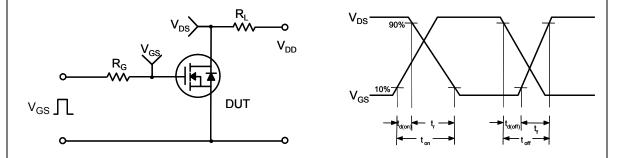


Figure 13. Resistive Switching Test Circuit & Waveforms

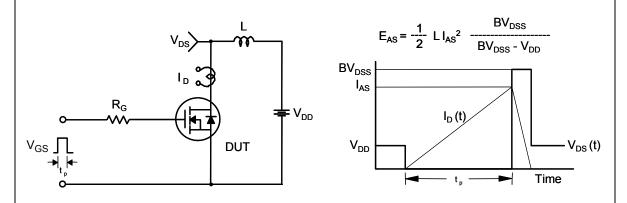
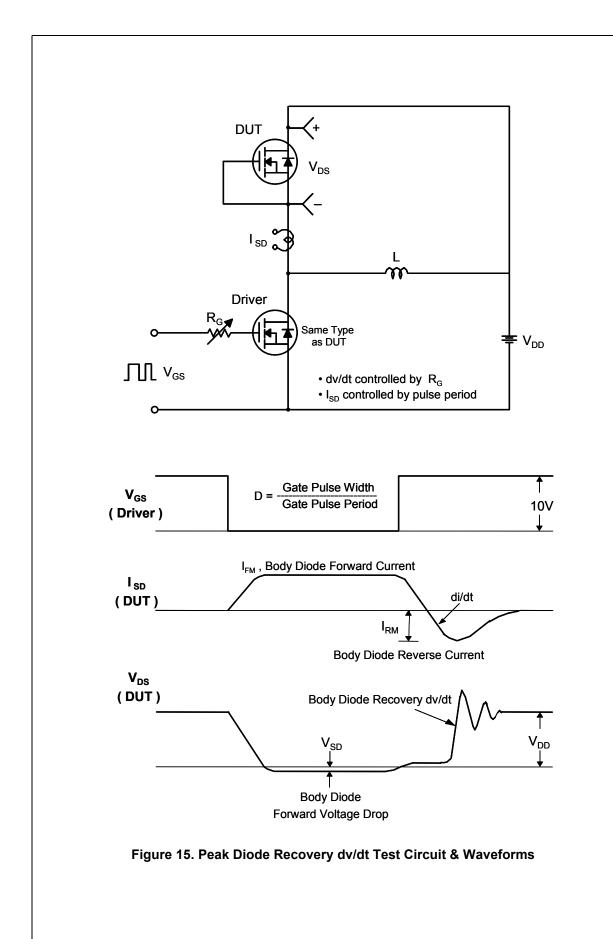
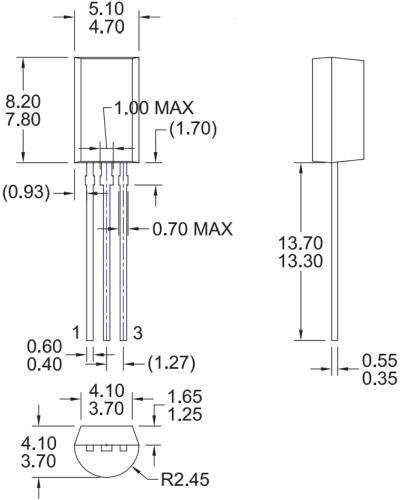


Figure 14. Unclamped Inductive Switching Test Circuit & Waveforms



Mechanical Dimensions



NOTES: UNLESS OTHERWISE SPECIFIED

- A) THIS PACKAGE DOES NOT CONFORM TO ANY STANDARD
- B) ALL DIMENSIONS ARE IN MILLIMETERS.
- DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.
- D) FORMERLY NAMED BD1409
- E) DRAWING FILE NAME: MKT-ZA03HREV1

Figure 16. TO92L, 3-Lead, 8 mm Long Body

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